

产品规格书

PRODUCT SPECIFICATION

Page: 1/11

产品规格：GJ-A1252 系列	No.: EN-005(2019-09)	Date Issued: Sep.22, 2019
Specification: GJ-1252 Series	Rev. : A.0	Date Revised:
1.25mm pitch/Disconnectable Crimp style connectors		Issued by: Engineering Dept.

Prepared by: <i>James.Hang</i>	Checked by: <i>James.Hang</i>	Reviewed by:	Approved by: <i>Liangdong.Yi</i>
-----------------------------------	----------------------------------	--------------	-------------------------------------

This document contains information that is proprietary to Gaojia Precision Electronics Not should not be used without written permission.

地址：广东省东莞市沙田镇沙田大道263号3单元101室

Add: Room 101, Unit 3, No.263, Sha Tin Avenue, Sha Tin Town, Dongguan City, Guangdong Province

电话：0769-81669553 传真：0769-81669553



Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

This specification is referred to the 1.25mm SMT series wire to board connector.

-INDEX-

- 1.0 Product Name/Part Number & Drawing Number.
- 2.0 Construction/Dimensions/Material & Surface Finish.
- 3.0 Characteristic.
- 4.0 Specimen.
- 5.0 Applicable Standards
- 6.0 Mechanical Performance.
- 7.0 Electrical Performance.
- 8.0 Environmental Performance.
- 9.0 Insertion Force & Retention Force Requirement.
- 10.0 **Caution**
- 11.0 Remark

REV. (版次)	Revision Record (改版變更原因)	Date(日期)	EC No



Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

1.0 Product Name/Part Number & Drawing Number:

	Product Name	Part Number	Drawing Number
	Crimp Terminal	GJ-A1252TM	GJ-A1252TM-P**
	Housing	GJ-A1252HM	GJ-A1252HM-**-A0N
Wafer	Straight	GJ-A1252WVS	GJ-A1252WVS-**-F0N
	Right Angle	GJ-A1252WRS	GJ-A1252WRS-**-F0N

Note: (xx) The number of the circuits.

2.0 Construction/Dimensions/Material & Surface Finish:

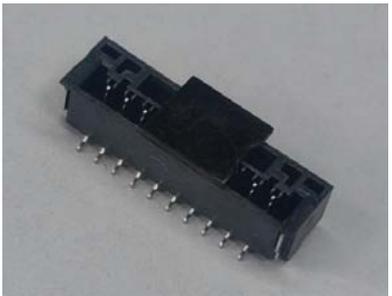
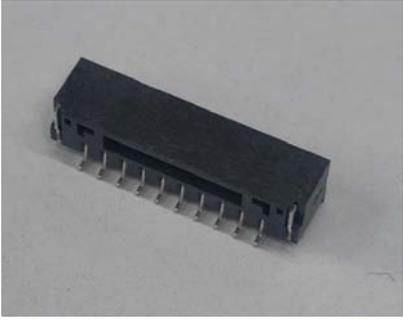
	Part Name	Material	Surface Finish
	Crimp Terminal	Phosphor Bronze	Tin Plated & Gold Flash
	Housing	Nylon 66	UL 94V-0
Wafer	Contacts	Phosphor Bronze	Bright Tin Plated
	Solder Tab	Phosphor Bronze	
	Base	LCP	UL 94V-0
	CAP	LCP	UL 94V-0

Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

3.0 Characteristic:

Item		Standard	
3.1	Rated Current	1A AC/DC (With AWG #28 is applied)	
3.2	Rated Voltage	50V AC/DC	
3.3	Ambient Temperature Range	Operating Temp.: -25~+85 ; Including 30°C Terminal Temperature Rise at rated Current . Storage temp.: -25~+85 ;	
3.4	Applicable Wire	3.4.1	Conductor Construction Size: AWG #32~#28
		3.4.2	Wire Insulation O.D.: 0.7mm~0.9mm
3.5	Applicable Printed Circuit Board (PCB)	3.5.1	SMT Layout: 1.25 ±0.05 mm per Pitch
		3.5.2	SMT Layout: 0.6minX1.7±0.05 mm for Pin Post
		3.5.3	SMT Layout: 1.0minX2.7±0.05 mm for Ear Buckle

4.0 Specimen:

Part Name/ Part Number/ Picture or Photograph			
Crimp Contact <i>GJ-A1252TM</i>		Wafer Straight <i>GJ-A1252WVS</i>	
Housing <i>GJ-A1252HM</i>		Wafer Right Angle <i>GJ-A1252WRS</i>	



Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

5.0 Applicable Standards:

MIL-STD-202 Methods by test of connectors for electronic equipment.
EIA 364 Testing method for electrical connectors.

6.0 Mechanical Performance:

Item		Test Condition	Requirement
6.1	Insertion & Retention Force	Insert and withdraw with connectors at the speed rate of 25mm/minute. (EIA 364-13) (A housing lock shall be removed for the measurement.)	Refer to paragraph 9.1
6.2	Crimp Tensile Strength(Axial)	Pull out the cable from contact terminal at the speed rate of 25±6mm/minute.	AWG#28 size wire 1.0Kgf min.
			AWG#30 size wire 0.5Kgf min.
			AWG#32 size wire 0.25Kgf min.
6.3	Contact Retention Force (in Housing)	Axial pullout force on the terminal in the housing at the speed rate of 25 ± 6 mm per minute.	0.7Kgf min.
6.4	Post Retention Force (in Base)	Axial pullout force on the square pin in the base at the speed rate of 25 ± 6 mm per minute. (EIA 364-29C)	0.3Kgf min.
6.5	Locking Strength	A socket housing and a header shall be mated. And then, the load shall be applied between them. The load to come them off each other shall be measured. (Testing speed: 1~ 5 mm/sec.)	2, 3 circuit 1.0 Kgf min.
			4 to 6 circuit 1.2 Kgf min.
			7 to 9 circuit 1.5 Kgf min.
			10 to 15 circuit 2.0 Kgf min.



Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

7.0 Electrical Performance:

Item	Test Condition	Requirement
7.1 Contact Resistance	A maximum voltage of 20mV and a maximum current of 10mA are applied to the Mate connectors. (EIA 364-23)	Contact Resistance: 30 milliohms Max.
7.2 Current Continuity	Each circuit of the connector shall be connected in series continuity meter shall detect current discontinuity longer than 1 microsecond during the vibration test.	No discontinuity current is longer than 1 microsecond.
7.3 Insulation Resistance	Apply 250V D/C to any two adjacent contacts to measure the insulation resistance. (EIA 364-21)	Insulation Resistance: Initial 100 megohms Min.
7.4 Withstanding Voltage	Apply 500V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the Mate connectors. (EIA 364-20)	No breakdown or flashover.



Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

8.0 Environmental Performance:

	Item	Test Condition	Requirement
8.1	Vibration	Frequency: 10~55~10 Hz/minute. Amplitude: 1.5 mm P-P. Direction: 1. Axis of up and down. 2. Axis of right the left. 3. Axis of front and back. Period: 2 hours for each direction. (EIA 364-28A-23)	Initial Contact Resistance : 30 milliohms Max. (After the test) Contact Resistance: 50 milliohms Max.
			No discontinuity current is longer than 1 microsecond.
8.2	Humidity Steady State	Temperature: 40±2°C. Humidity: 90%~95% (RH). Period: 96 hours continuously. (EIA 364-31)	(After the test) Contact Resistance: 50 milliohms Max.
			(After the test) Insulation Resistance: 100 Megohms Min.
			(After the test) Withstanding Voltage : No breakdown or flashover
8.3	Thermal Shock	One Cycle Consists Of: -55 +0/-3°C for 30 minutes. → Room Temp.5 minutes 85+3/-0°C for 30 minutes. → Room Temp.5 minutes Total Cycles: 5 Cycles. (EIA 364-32)	Same as paragraph 8.2



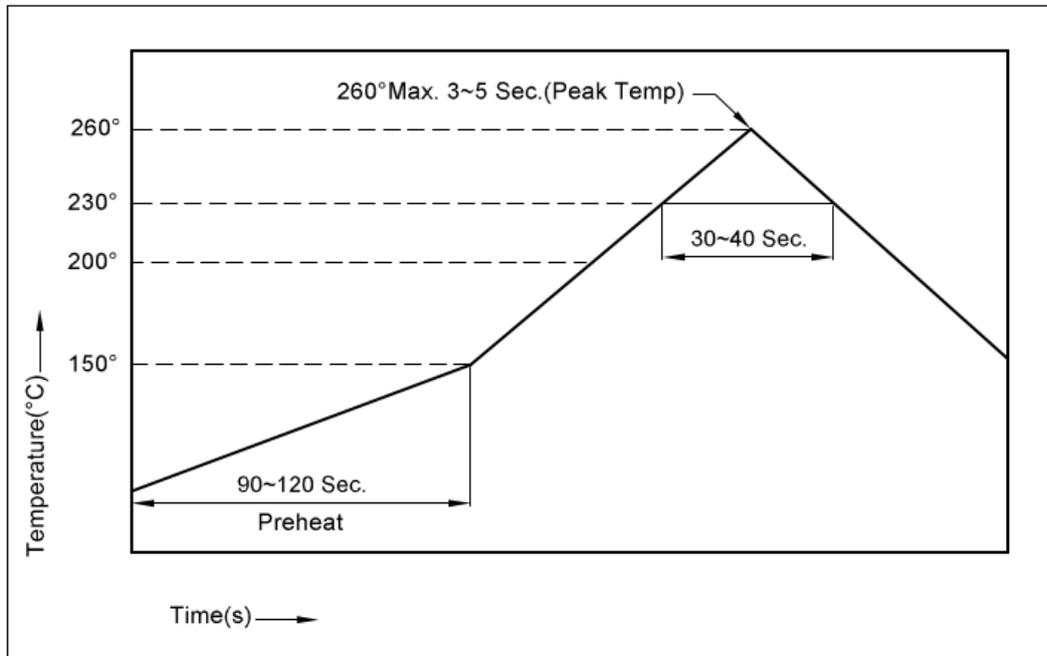
Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

Item		Test Condition	Requirement
8.4	Heat Aging	Temperature: 85±2℃. Period: 96 hours continuously. (EIA 364-17)	Contact Resistance: 50 milliohms Max. after the test.
8.5	Salt Spray	Temperature: 35±2℃. Density: 5 % in weight. Period: Terminal or contact (Stamping after tin plated for 8 hours) ; Terminal or contact (Stamping before tin plated for 24 hours) (EIA 364-26)	(After the test) Contact Resistance: 50 milliohms Max
8.6	Solder Ability	Solder Temperature: 245 ± 5℃. Immersion Period: 3±0.5 Seconds Method : 1.5mm From Square Pin Tip. (EIA 364-52)	Solder entirely 95% of immersed area must show no voids or pinholes.

Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

Item	Test Condition	Requirement
8.7 Resistance To Soldering Heat	By reflow soldering: Refer to Temperature Profile 8.8.1	Not deformation or damage.
	By soldering iron: 350 ± 5°C 3±0.5 Seconds. Method : 0.5mm From Terminal Tip and Solder Tab Tip	

8.7.1 Temperature Profile:





Type Document	Product Specification	Revised / Edition	A
Date Issued	2019/09/22	Data Revised	
Subject: GJ-A1252HM-**-A0N GJ-A1252TM-P** GJ-A1252WVS-**-F0N GJ-A1252WRS-**-F0N Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

9.0 Insertion Force (I.F.) & Retention Force (R.F.)

9.1 Requirement:

No. Of Circuits	AT INITIAL		AT 30TH	No. Of Circuits	AT INITIAL		AT 30TH
	I.F. (Max)	R.F. (Min)	R.F. (Min)		I.F. (Max)	R.F. (Min)	R.F. (Min)
02	1.7	0.05	0.05	09	2.4	0.40	0.40
03	1.8	0.10	0.10	10	2.5	0.45	0.45
04	1.9	0.15	0.15	11	2.6	0.50	0.50
05	2.0	0.20	0.20	12	2.7	0.55	0.55
06	2.1	0.25	0.25	13	2.8	0.60	0.60
07	2.2	0.30	0.30	14	2.9	0.65	0.65
08	2.3	0.35	0.35	15	3.0	0.70	0.70

(Kg/f)

10.0 Caution : Parts are made of hydrophilic Polyamide LCP and apt to absorb moisture. Once the vacuum-packing unpacked, please keep parts in the environment of **temperature < 30°C/ humidity < 60% RH**, and send to re-flowing **within 72 hours** to prevent parts blistered or deformed during soldering.

11.0 Remark: Any change or revision for the product specification will not be announced in advance. Please contact our sales representative for the latest information.